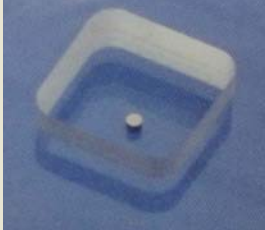


The TGV technology that achieves complete sealing implemented on spot facing bottom surface transparent glass. (page 75)



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**ASIA ELECTRONICS INDUSTRY** (ISSN 1342-422X) is published monthly by Dempa Publications, Inc., 1-11-15 Higashi Gotanda, Shinagawa-ku, Tokyo 141-8715, Japan Tel: +81-3-3445-6111 Fax: +81-3-3447-4666. Editorial e-mail: may@dempa.co.jp; Subscription e-mail: circmnl@pltdsl.net. The magazine is distributed free to qualified subscribers in ASEAN countries (Thailand, Indonesia, The Philippines, Malaysia, Singapore, Brunei, Vietnam, Myanmar, Cambodia and Laos), as well as Korea, Taiwan and Hong Kong.

Paid air mail subscription is available to non-qualified subscribers in the Asian and Pacific regions for US\$150 per year and US\$260 for two years. For other areas, air mail subscription fees are US\$160 per year and US\$280 for two years. Paid subscription is accepted at <http://aei.dempa.net/paidsub/subscription.html>

Send address corrections to Dempa Publications, Inc., c/o Quantum Solutions (HK) Ltd. Unit 3-6, G/F Pacific Trade Centre, 2 Kai Hing Road, Kowloon Bay, Kowloon, Hong Kong

President & Publisher: Tetsuo Hirayama

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